


TRANSMITTAL OF FORMAL DRAWINGSDocket No.
YOR920030183US1 (16675)In Re Application Of: **Victor Chan, et al.**

JAN 21 2004

Serial No.
107674,644Filing Date
09/30/03Confirmation No.
UnassignedExaminer
UnassignedArt Unit
UnassignedInvention: **THREE DIMENSIONAL CMOS INTEGRATED CIRCUITS HAVING DEVICE LAYERS BUILT ON DIFFERENT CRYSTAL ORIENTED WAFERS**Address to:
**Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450**

Transmitted herewith are:

2 sheets of formal drawing(s) for this application.☒ Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c).

Signature
**Leslie S. Szivos
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(516) 742-4343****LSS/rjl**Dated: **January 15, 2004**I certify that this document and attached formal drawings are being deposited on **January 15, 2004** with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.
*Signature of Person Mailing Correspondence***Leslie S. Szivos***Typed or Printed Name of Person Mailing Correspondence*